

OPTICAL FABRICATION CAPABILITIES & TOLERANCES*



	<u>BEST</u>	<u>TYPICAL</u>
X-RAY CRYSTALLOGRAPHIC ORIENTATION:	To within 10" of arc	15'
SURFACE QUALITY:	10/5, Laser	20/10
WAFERING: PARTS POLISHED TO:		
Thickness:	+/-2 μm	+/-5 μm
Flatness:	$\lambda/10$	$\lambda/2$
Parallelism:	<5"	<60"
DICING:		
Maximum Depth of Cut:	22 mm	19.5 mm
Perpendicularity of Cuts:	+/-5'	+/-20'
Parallelism of Cuts:	<5'	<20'
Dimensional Tolerance:	+/-2 μm	+/-10 μm
MATERIALS FABRICATED:	YVO ₄ , Ge, PbMoO ₄ , TeO ₂ , Calcite, LiNbO ₃ , SiO ₂ , TiO ₂ & most glasses	
TYPES OF PARTS:	Windows, Wafers, Prisms, Diced Chips & Microprisms	

*Tolerances are size & material dependent.